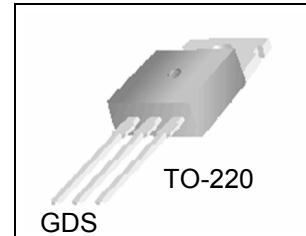
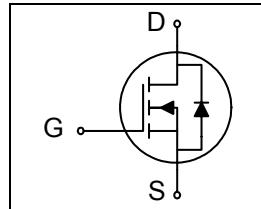


**Features**

- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- High di/dt Capability
- Improved Gate Charge
- Wide Expanded Safe Operating Area

**Application**

- DC-DC Converters
- UPS & Monitors



|              |          |
|--------------|----------|
| $BV_{DSS}$   | = 100V   |
| $R_{DS(on)}$ | = 0.026Ω |
| Typ          | = 0.023Ω |
| $I_D$        | = 50A    |

**Absolute Maximum Ratings** ( $T_C = 25^\circ\text{C}$  Unless Otherwise Specified)

| Symbol         | Characteristic   | Value       | Units               |
|----------------|--|-------------|---------------------|
| $V_{DSS}$      | Drain-Source Voltage   | 100         | V                   |
| $I_D$          | Continuous Drain Current ( $T_C = 25^\circ\text{C}$ )                      | 50          | A                   |
|                | Continuous Drain Current ( $T_C = 100^\circ\text{C}$ )                     | 35.3        |                     |
| $I_{DM}$       | Drain Current-Pulsed   | (1) 200     | A                   |
| $V_{GS}$       | Gate-to-Source Voltage   | $\pm 20$    | V                   |
| $E_{AS}$       | Single Pulsed Avalanche Energy   | (2) 550     | mJ                  |
| $I_{AR}$       | Avalanche Current  | (1) 50      | A                   |
| $E_{AR}$       | Repetitive Avalanche Energy  | (1) 15      | mJ                  |
| $dv/dt$        | Peak Diode Recovery $dv/dt$  | (3) 6       | V/ns                |
| $P_D$          | Total Power Dissipation ( $T_C = 25^\circ\text{C}$ )                       | 150         | W                   |
|                | Linear Derating Factor   | 1           | W/ $^\circ\text{C}$ |
| $T_J, T_{STG}$ | Operating Junction and Storage Temperature Range                           | -55 to +175 | $^\circ\text{C}$    |
| $T_L$          | Maximum Lead Temp. for soldering purposes,<br>1/8" from case for 5-seconds | 300         | $^\circ\text{C}$    |

**Thermal Characteristics**

| Symbol          | Characteristic           | Typ. | Max. | Units              |
|-----------------|--------------------------|------|------|--------------------|
| $R_{\theta JC}$ | Junction-to-Case         | --   | 1    | $^\circ\text{C/W}$ |
| $R_{\theta CS}$ | Junction-to-Case-to-Sink | 0.5  | --   |                    |
| $R_{\theta JA}$ | Junction-to-Ambient      | --   | 62.5 |                    |

**Electrical Characteristics** ( $T_C = 25^\circ\text{C}$  unless otherwise specified)

| Symbol                       | Characteristic                          | Min. | Typ.  | Max.  | Units               | Test Condition   |
|------------------------------|---|------|-------|-------|---------------------|--|
| $BV_{DSS}$                   | Drain-Source Breakdown Voltage          | 100  | --    | --    | V                   | $V_{GS} = 0V, I_D = 250\mu\text{A}$                          |
| $\Delta BV_{DSS}/\Delta T_J$ | Breakdown Voltage Temp. Coeff.          | --   | 0.11  | --    | V/ $^\circ\text{C}$ | $I_D = 250\mu\text{A}$                                       |
| $V_{GS(\text{th})}$          | Gate Threshold Voltage                  | 2.5  | --    | 4.0   | V                   | $V_{DS} = V_{GS}, I_D = 250\mu\text{A}$                      |
| $I_{GSS}$                    | Gate-Source Leakage, Forward            | --   | --    | 100   | nA                  | $V_{GS} = 20V$   |
|                              | Gate-Source Leakage, Reverse            | --   | --    | -100  |                     | $V_{GS} = -20V$  |
| $I_{DSS}$                    | Drain-to-Source Leakage Current         | --   | --    | 1     | $\mu\text{A}$       | $V_{DS} = 100V$  |
|                              |   | --   | --    | 10    |                     | $V_{DS} = 80V, T_C = 125^\circ\text{C}$                      |
| $R_{DS(\text{on})}$          | Static Drain-Source On-State Resistance | --   | 0.023 | 0.026 | $\Omega$            | $V_{GS} = 10V, I_D = 25\text{A}$<br>(4)                      |
| $g_{fs}$                     | Forward Transconductance                | --   | 37    | --    | $\text{S}$          | $V_{DS} = 25V, I_D = 25\text{A}$<br>(4)                      |
| $C_{iss}$                    | Input Capacitance                       | --   | 2060  | 2680  | pF                  | $V_{GS} = 0V, V_{DS} = 25V,$<br>$f = 1\text{MHz}$            |
| $C_{oss}$                    | Output Capacitance                      | --   | 325   | 420   |                     |  |
| $C_{rss}$                    | Reverse Transfer Capacitance            | --   | 56    | 73    |                     |  |
| $t_{d(on)}$                  | Turn-On Delay Time                      | --   | 17.5  | 45    | ns                  | $V_{DD} = 50V, I_D = 50\text{A},$<br>$R_G = 25\Omega$ (4)(5) |
| $t_r$                        | Rise Time                               | --   | 108   | 226   |                     |  |
| $t_{d(off)}$                 | Turn-Off Delay Time                     | --   | 136   | 282   |                     |  |
| $t_f$                        | Fall Time                               | --   | 137   | 284   |                     |  |
| $Q_g$                        | Total Gate Charge                       | --   | 57.5  | 75.0  | nC                  | $V_{DS} = 80V, V_{GS} = 10V,$<br>$I_D = 50\text{A}$ (4)(5)   |
| $Q_{gs}$                     | Gate-Source Charge                      | --   | 12.0  | --    |                     |  |
| $Q_{gd}$                     | Gate-Drain("Miller") Charge             | --   | 21.6  | --    |                     |  |

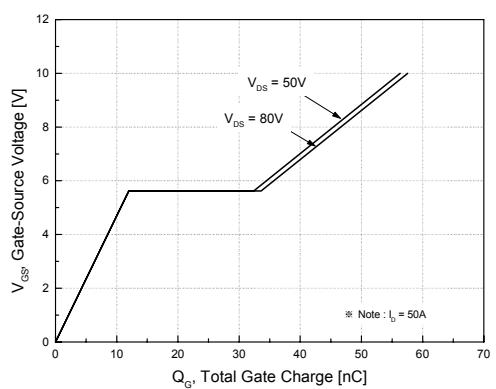
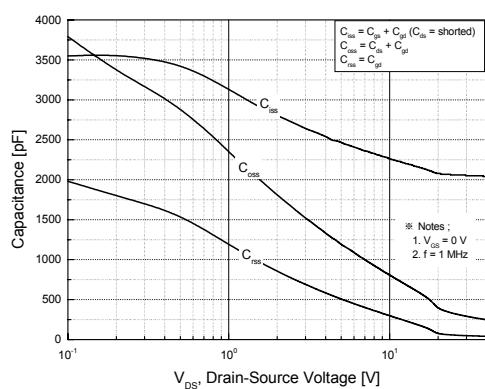
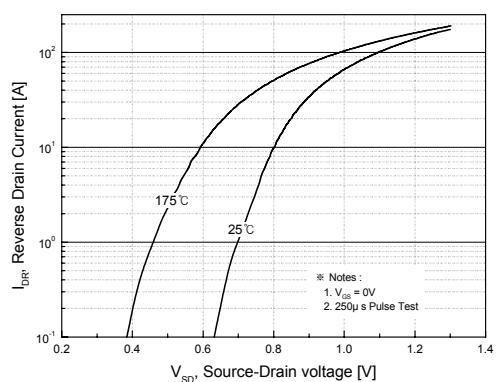
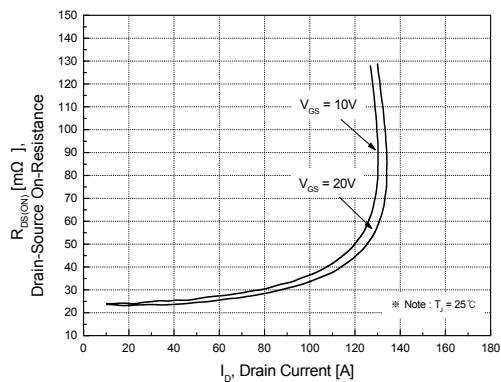
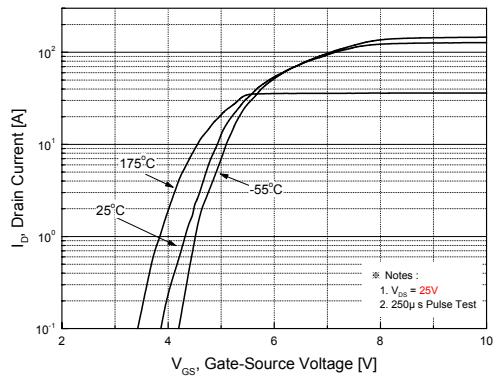
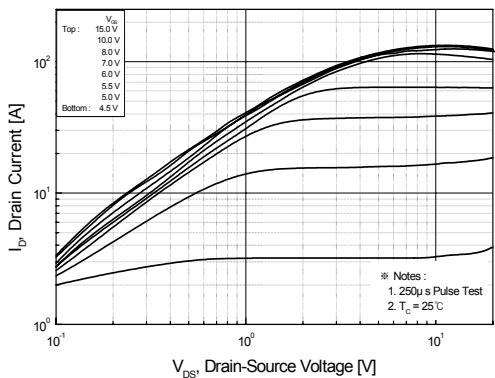
**Source-Drain Diode Ratings and Characteristics**

| Symbol   | Characteristic            | Min. | Typ. | Max. | Units | Test Condition  |
|----------|---------------------------|------|------|------|-------|---|
| $I_S$    | Continuous Source Current | --   | --   | 50   | A     | Integral reverse pn-diode in the MOSFET                                       |
| $I_{SM}$ | Pulsed Source Current (1) | --   | --   | 200  |       |   |
| $V_{SD}$ | Diode Forward Voltage (4) | --   | --   | 1.3  |       |   |
| $t_{rr}$ | Reverse Recovery Time     | --   | 93   | --   | ns    | $I_F = 50\text{A}, V_{GS} = 0V,$<br>$dI_F / dt = 100\text{A}/\mu\text{s}$ (4) |
| $Q_{rr}$ | Reverse Recovery Charge   | --   | 323  | --   | nC    |   |

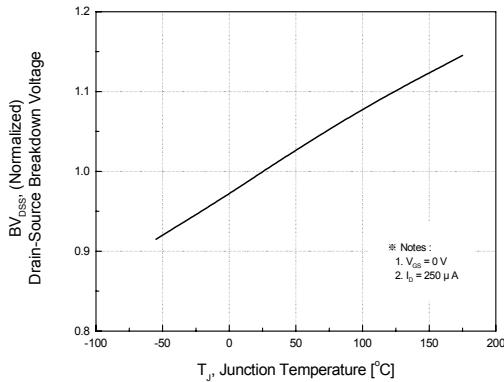
**Notes:**

- (1). Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- (2).  $L = 330\mu\text{H}, I_{AS} = 50\text{A}, V_{DD} = 25V, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
- (3).  $I_{SD} \leq 50\text{A}, di/dt \leq 300\text{A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$
- (4). Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$
- (5). Essentially Independent of Operating Temperature

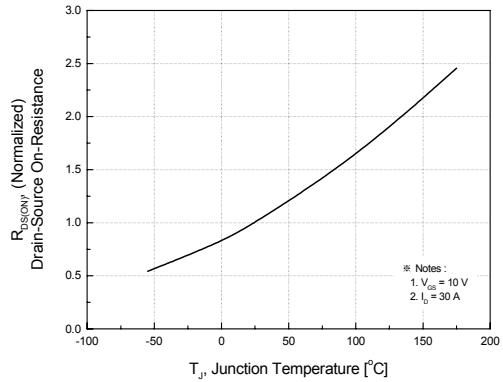
## Typical Characteristics



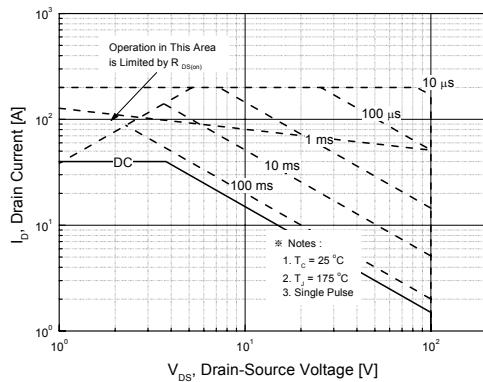
## Typical Characteristics



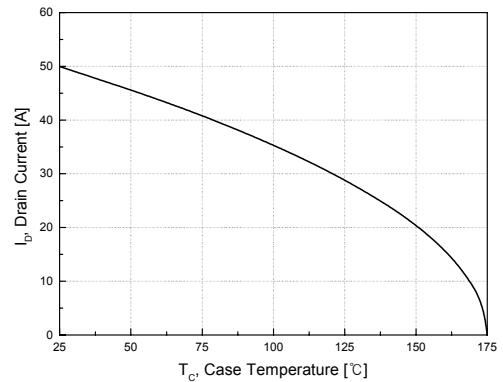
**Fig 7. Breakdown Voltage Variation vs. Temperature**



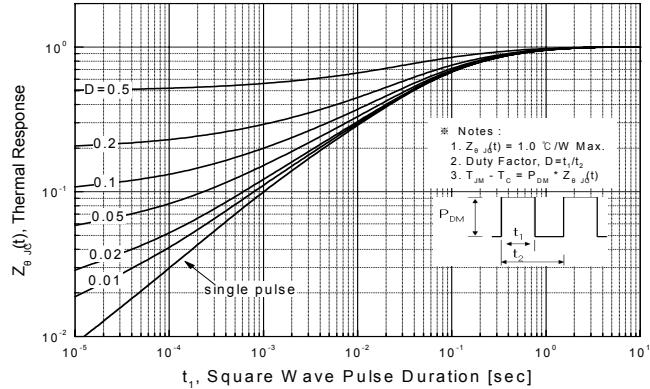
**Fig 8. On-Resistance Variation vs Temperature**



**Fig 9. Maximum Safe Operating Area**

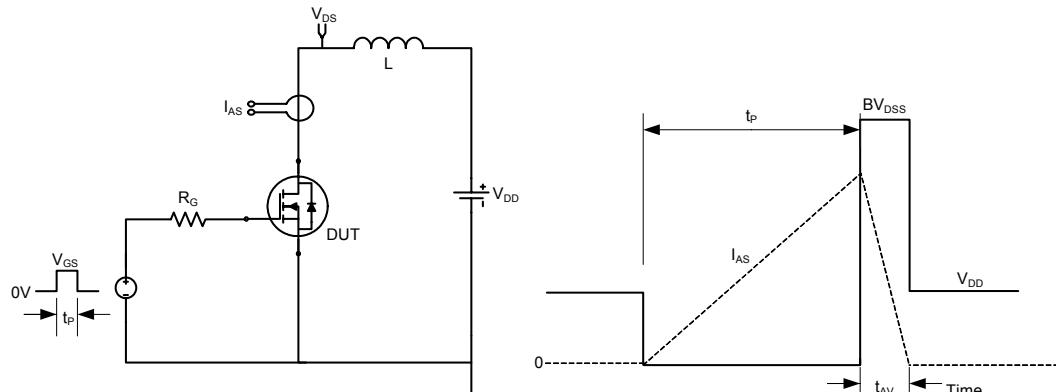


**Fig 10. Maximum Drain Current vs. Case Temperature**



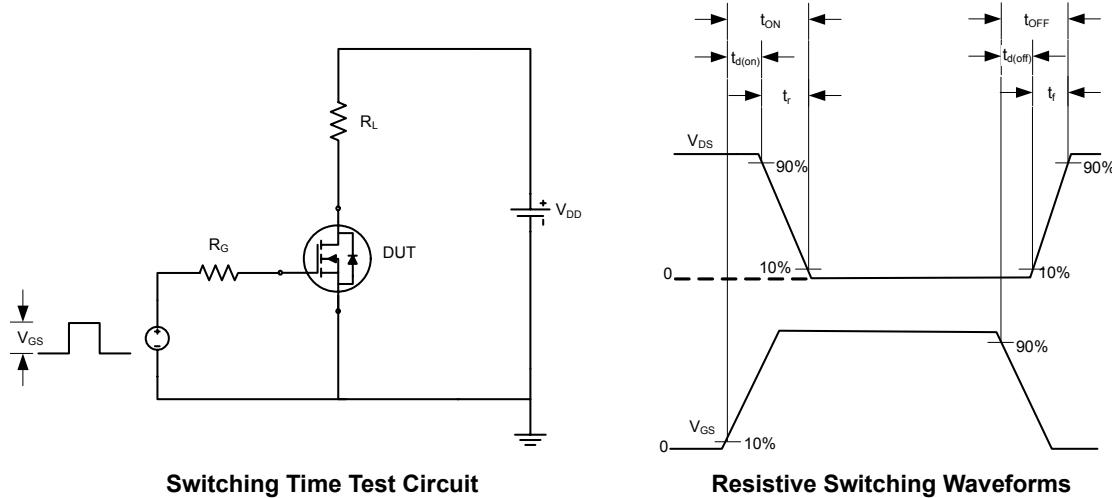
**Fig 11. Transient Thermal Response Curve**

### Test Circuit and waveform



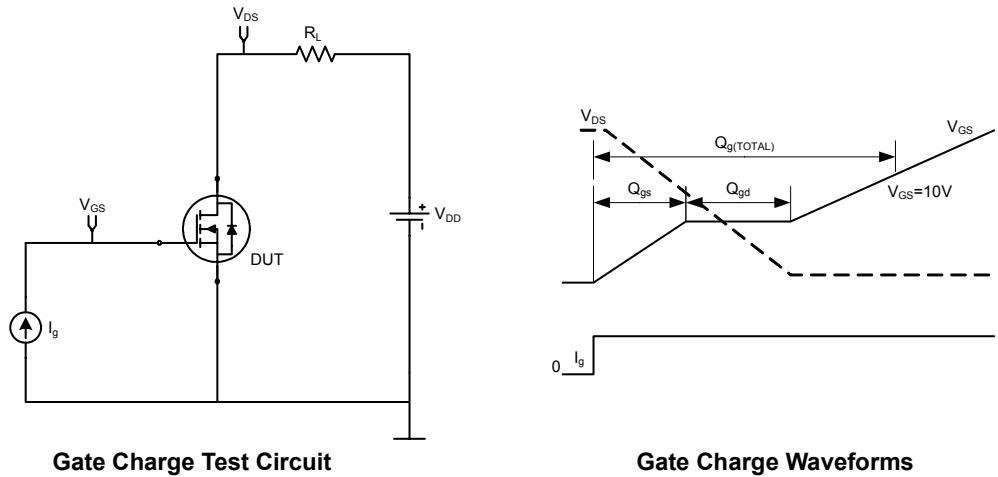
Unclamped Energy Test Circuit

Unclamped Energy Waveforms



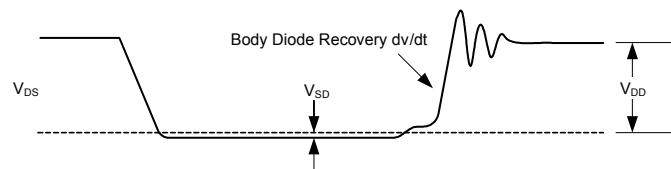
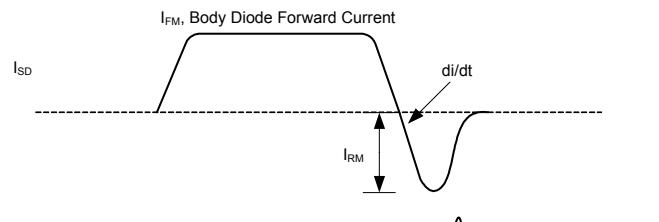
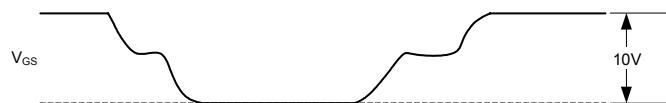
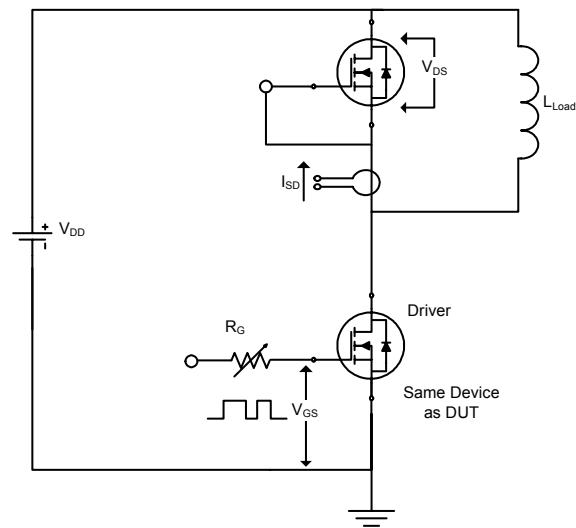
Switching Time Test Circuit

Resistive Switching Waveforms



Gate Charge Test Circuit

Gate Charge Waveforms



**Body Diode Recovery dv/dt Test Circuit and Waveform**

## Package Dimensions

**TO-220**

